



Preliminary Product Information Sheet

EPO-TEK® GE116-1

Note: These are typical properties to be used as a guide only, not a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.

Date: September 2017
Rev: V
No. of Components: Single
Mix Ratio by Weight: N/A
Specific Gravity: 1.12
Pot Life: 28 Days
Shelf Life- Bulk: One year at -40°C

Recommended Cure: 150°C / 1 Hour

Minimum Alternative Cure(s):
May not achieve performance properties listed below
150°C / 10 Minutes

NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

Product Description: A single component, thixotropic, electrically and thermally insulating epoxy adhesive designed for bonding SMDs to the PCB. It can be used for electronic assembly in many devices including consumer electronics, cell phone, telecommunications, automotive, and scientific/OEM. A lower viscosity version of EPO-TEK® GE116 designed for high speed dispensing without stringing or tailing.

MATERIAL CHARACTERISTICS*:

PHYSICAL PROPERTIES:	Cure condition: 150°C / 1 Hour	
Color (before cure):	Red	
Consistency:	Smooth paste	
Viscosity (23°C) @ 20 rpm:	16,050	cPs
Thixotropic Index:	3.1	
Glass Transition Temp:	44	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Shore D Hardness:	60	
Lap Shear @ 23°C:	573	psi
Die Shear @ 23°C:	7.1	Kg
Degradation Temp:	329	°C
Weight Loss:		
	@ 200°C:	0.17 %
	@ 250°C:	1.72 %
	@ 300°C:	6.27 %
Suggested Operating Temperature:	< 260	°C (Intermittent)
Particle Size:	≤ 20	microns

The data above is INITIAL only - it may be changed at any time, for any reason without notice to anyone. It is provided only as a guide for evaluation/consideration.

* These material characteristics are typical properties that are based on a limited number of samples/batches. All properties are based on the cure indicated above. Some properties may vary as manufactured quantities are scaled up to commercialized production levels.